



8755 W. Higgins Road  
Suite 500  
Chicago, Illinois USA 60631

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May 21<sup>st</sup>, 2021

RE: PCN # ESU270-64 –AQ3130-01ETG additional backend location approval

To our valued customers,

Littelfuse would like to notify you of an additional approved backend location for AQ3130-01ETG TVS Diode Array (SPA® Diodes) product. This new backend factory in China is fully approved for all assembly, test, and packing operations. There are no changes to fit, form, and function of the finished product.

Qualification efforts are completed, new factory is online for immediate shipments. Please see the documentation in the following pages for change details.

The affected product has been fully qualified in accordance with established performance and reliability criteria. Full qualification data and/or samples will be available upon request.

**Form, fit, function changes: None**  
**Part number changes: None**  
**Effective date: August 20<sup>th</sup>, 2021 or sooner**  
**Replacement products: N/A**  
**Last time buy: N/A**

This notification is for your information and acknowledgement. If you have any other questions or concerns, please contact Sophia Hu, Assistant Product Manager.

We value your business and look forward to assisting you whenever possible.

Best Regards,

Sophia Hu  
TVS Diode Array Assistant Product Manager  
Semiconductor Business Unit, Wuxi, China  
+86 510 85277701 - 7653  
[shu@littelfuse.com](mailto:shu@littelfuse.com)





**Prepared By** : Jordan Hsieh-Product Engineering Manager,  
Raider Chen-Product Engineer, Sophia Hu-Associate Product Manager  
**Date** : 2021/5/12  
**Device** : AQ3130-01ETG  
**Revision** : A

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### **1.0 Objective:**

The purpose of this document is to qualify an additional assembly supplier for AQ3130-01ETG. Summarize the physical, electrical and reliability test performed in qualification lots.

### **2.0 Applicable Devices:**

**2.1 Product name: AQ3130-01ETG**

### **3.0 Assembly, Process & Material Differences/Changes:**

#### **3.1 Assembly Changes**

No change of assemble process.

#### **3.2 Process Changes**

No change of process method.

#### **3.3 Material Change**

AQ3130-01ETG			
Item	Original	New	Change or not
Lead frame	C7025	Efect64T	Yes
Die Attach Material	8006NS	8006NS	No
Wire	Gold	Gold	No
Mold Compound	CEL-9220HF10	G770HCD	Yes
Plating	PPF	PPF	No

### **4.0 Packing Method**

No change of packing method.

### **5.0 Physical Differences/Changes:**

No change of this item.

**6.0 Reliability Test Results Summary:**

**6.1 AQ3130-01ETG summary report:**

Test Items	Condition	S/S	Results	ETR #
Pre-conditioning (PC)	JESD22-A113	308 each lot	0/924	79803 78492 155379
DC Blocking (HTRB)	Bias = VRWM, Ta = 150°C, Duration = 1008 Hours	77 each lot	0/231	
Temperature Cycle (TC)	Ta = -55°C to +150°C, Duration = 1000 Cycles	77 each lot	0/231	
Temperature/Humidity (H3TRB)	Ta = 85°C, 85% RH, Bias = VRWM, Duration = 1008 Hours	77 each lot	0/231	
Autoclave (AC)	Ta = 121°C, 100%RH, 2ATM, Duration = 96 Hours	77 each lot	0/231	
Resistance to Solder Heat (RSH)	260°C, 10 sec, M-2031	10 each lot	0/30	
Moisture Sensitivity Level (MSL)	Per Jedec J-STD-020D Level 1	308 each lot	0/924	
Solderability (SD)	ANSI-J-STD-002	10 each lot	0/30	

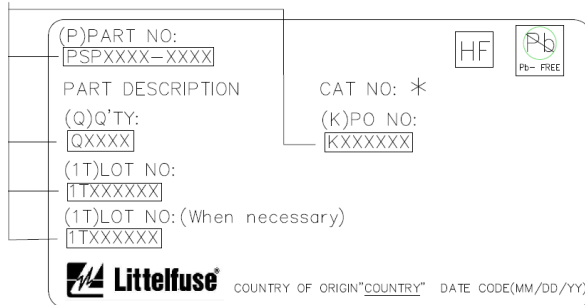
**7.0 Electrical Characteristic Summary:**

No change in electrical characteristics. Characterization data is available upon request.

**8.0 Changed Part Identification:**

Both were qualified suppliers and it can be identified by code of CAT NO on the label.

Barcode Scanning Result



**9.0 Approvals:**

**Sophia Hu**  
SPA Assistant Product Manager  
Littelfuse, Wuxi

**Jordan Hsieh**  
SPA Product Manager  
Littelfuse, HsinChu

**Raider Chen**  
SPA Product Engineer  
Littelfuse, HsinChu